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Renesas Technology Corp. Customer Support Dept. April 1, 2003



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2SB1059

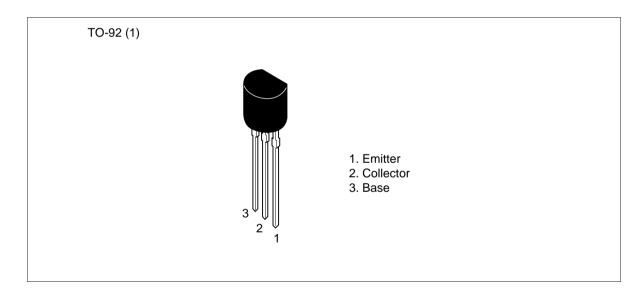
Silicon PNP Epitaxial



Application

- Low frequency power amplifier
- Complementary pair with 2SD1490

Outline



2SB1059

Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	-70	V
Collector to emitter voltage	V _{CEO}	– 50	V
Emitter to base voltage	V_{EBO}	-6	V
Collector current	I _c	– 1	А
Collector power dissipation	P _c	0.75	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

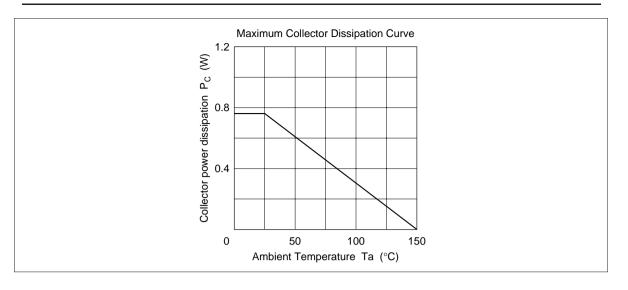
Electrical Characteristics ($Ta = 25^{\circ}C$)

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-70	_	_	V	$I_{c} = -10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-50	_	_	V	$I_{C} = -1 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	-6	_	_	V	$I_{E} = -10 \ \mu A, \ I_{C} = 0$
Collector cutoff current	I _{CBO}	_	_	-1	μΑ	$V_{CB} = -55 \text{ V}, I_{E} = 0$
Emitter cutoff current	I _{EBO}	_	_	-0.2	μΑ	$V_{EB} = -6 \text{ V}, I_{C} = 0$
DC current transfer ratio	h _{FE} *1	100	_	320		$V_{CE} = -2 \text{ V}, I_{C} = -0.1 \text{ A}$
Collector to emitter saturation voltage	$\boldsymbol{V}_{\text{CE(sat)}}$	_	_	-0.6	V	$I_{c} = -1 A, I_{B} = -0.1 A$
Gain bandwidth product	f _T	_	65	_	MHz	$V_{CE} = -2 \text{ V}, I_{C} = -10 \text{ mA}$
Collector output capacitance	Cob	_	35	_	pF	$V_{CB} = -10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$

Note: 1. The 2SB1059 is grouped by $h_{\rm FE}$ as follows.

В	С
100 to 200	160 to 320

See characteristic curves of 2SB740.



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